

NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. 'e' REPRESENTS THE BASIC SOLDER BALL GRID PITCH.

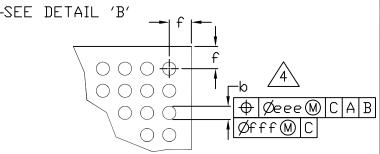
SIDE VIEW

-SEATING PLANE

'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE AND SYMBOL 'N' IS THE NUMBER OF BALLS AFTER DEPOPULATING.

DETAIL "A"

- 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER AFTER REFLOW PARALLEL TO PRIMARY DATUM [].
- DIMENSION 'ddd' IS MEASURED PARALLEL TO PRIMARY DATUM [] .
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 7. PACKAGE SURFACE SHALL BE MATTE FINISH.
- 8. SUBSTRATE MATERIAL BASE IS BT RESIN.
- 9. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
- 10. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
- 11. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PHFREE (+) PKG. CODES.
- -DRAWING NOT TO SCALE-



DETAIL "B"

DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
Α	1.08	1.20	1.32
A1	0.36		0.46
A2	0.53 REF		
A3	0.26 REF		
D	9.90	10.00	10.10
D1	8.00 BSC		
E	9.90	10.00	10.10
E1	8.00 BSC		
Ь	0.44	0.54	0.64
е	1.00 BSC		
f	0.90	1.00	1.10
aaa			0.20
bbb			0.35
ddd			0.10
eee			0.25
fff			0.10
М	9		
N	81		
Pkg. Code	X8100-2, X8100-3		

TITLE:

PACKAGE DUTLINE,

81 BALLS CSBGA, 10×10×1.2mm

APPROVAL DOCUMENT CONTROL NO. 21-0394

REV. 1